

9/10/13

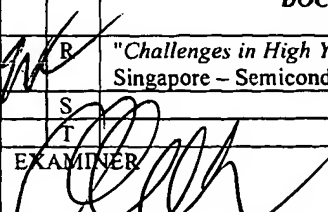
<b>PTO-1449</b>  <b>Information Disclosure Citation In an Application</b>	Application No. <b>To be Assigned</b> 10/690921	Applicant(s) <b>Howard, et al.</b>	
	Docket Number <b>TI-36332 (032350.B531)</b>	Group Art Unit <b>To be Assigned</b> 2815	Filing Date <b>Sept. 10, 2003</b>

**U.S. PATENT DOCUMENTS**

	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
A						
B						
C						
D						
E						
F						
G						
H						
I						
J						
K						
L						
M						
N						

**FOREIGN PATENT DOCUMENTS**

	DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
O							
P							
Q							

	<b>DOCUMENT (Including Author, Title, Source, and Pertinent Pages)</b>	<b>DATE</b>
	"Challenges in High Yield, Fine Pitch Solder Ball Attachment", by Ivy Qin, et al., SEMI - Semicon Singapore - Semiconductor Packaging Conference, pp. 1-10	05/2001
<b>EXAMINER</b>	<b>DATE CONSIDERED</b> 9/18/04	

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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